



Docket No.: 246722US2SRD DIV

**OBLON**  
**SPIVAK**  
**McCLELLAND**  
**MAIER**  
**&**  
**NEUSTADT**  
**P.C.**

ATTORNEYS AT LAW

COMMISSIONER FOR PATENTS  
ALEXANDRIA, VIRGINIA 22313

RE: Application Serial No.: 10/736,593

Applicants: Koji USUDA, et al.

Filing Date: December 17, 2003

For: SEMICONDUCTOR DEVICE AND METHOD OF  
MANUFACTURING THE SAME

Group Art Unit: 2814

Examiner: WILLIE, DOUGLAS A.

SIR:

Attached hereto for filing are the following papers:

**COMMENTS ON EXAMINER'S STATEMENT OF REASONS FOR ALLOWANCE**

Our check in the amount of \$0.00 is attached covering any required fees. In the event any variance exists between the amount enclosed and the Patent Office charges for filing the above-noted documents, including any fees required under 37 C.F.R. 1.136 for any necessary Extension of Time to make the filing of the attached documents timely, please charge or credit the difference to our Deposit Account No. 15-0030. Further, if these papers are not considered timely filed, then a petition is hereby made under 37 C.F.R. 1.136 for the necessary extension of time. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

OBLON, SPIVAK, McCLELLAND,  
MAIER & NEUSTADT, P.C.

*Joseph Scafetta Jr.*  
\_\_\_\_\_  
Marvin J. Spivak

Registration No. 24,913

Joseph Scafetta, Jr.

Registration No. 26,803

Katherine D. Pauley

Registration No. 50,607

Customer Number

22850

(703) 413-3000 (phone)  
(703) 413-2220 (fax)

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IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF

KOJI USUDA, ET AL.

: EXAMINER: WILLE, DOUGLAS A.

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COMMENTS ON EXAMINER'S STATEMENT  
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SIR:

The "Statement of Reasons for Allowance" included at page 2 of the Notice of Allowance states "a method is claimed for forming a device by flip chip bonding a two layer substrate to another substrate ...." Applicants note that the "flip chip bonding a two layer substrate to another substrate" is not recited in either of the independent claims. Applicants therefore respectfully request that a revised Statement of Reasons for Allowance be issued without reference to subject matter not recited in the independent claims.

Respectfully submitted,

OBLON, SPIVAK, McCLELLAND,  
MAIER & NEUSTADT, P.C.

*Katherine D. Pauley*

Eckhard H. Kuesters  
Registration No. 28,870  
Attorney of Record  
Katherine D. Pauley  
Registration No. 50,607

**22850**

Tel No: (703) 413-3000  
Fax No: (703) 413-2220  
EHK:KDP:pja